

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) A socket for a semiconductor device, comprising:
a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals,
said semiconductor device being one of a plurality of semiconductor devices having
contour dimensions different from one another ~~one of a plurality of semiconductor~~
~~devices having contour dimensions different from each other, to be electrically~~
~~connected to contact terminals;~~

a pressing member having an a touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, said pressing member being driven by a pressing member driving mechanism in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section, for holding said semiconductor device in said semiconductor device placement section; and

wherein, when said pressing member driving mechanism moves said touch portion of said pressing member ~~to be away from said semiconductor device~~ to a position ~~in readiness at~~ in which said touch portion of said pressing member ~~is not interfered with~~ does not contact said semiconductor device upon the attachment or detachment of said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket body via an opening of said socket body.

2. (Currently Amended) A socket for a semiconductor device, comprising:

a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals, said semiconductor device being one of a plurality of semiconductor devices having contour dimensions different from one another ~~one of a plurality of semiconductor devices having contour dimensions different from each other, to be electrically connected to contact terminals;~~

a pressing member having ~~an~~ a touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, for holding said semiconductor device in said semiconductor device placement section; and

a cover member supported by said socket body in a movable manner for ~~bring~~ bringing said touch portion of said pressing member into contact with or away from said semiconductor device in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section;

wherein, said cover member and said socket body have openings, respectively, so that when said cover member causes said touch portion of said pressing member to ~~be away from said semiconductor device~~ move to a position in ~~readiness at~~ which said touch portion of said pressing member ~~is not interfered with~~ does not contact said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket body via one or more of the openings of the socket body.

3. (Currently Amended) A socket for a semiconductor device as claimed in claim 1, wherein ~~said socket comprising:~~

said pressing member is a first pressing member, said first pressing member having a first proximal end supported in a moveably rotational manner at one end of said socket body, said touch portion is a first touch portion and is coupled to said first proximal end, and the movement of said first proximal end causes said first touch portion to contact said semiconductor device so that said semiconductor device is pressed toward said contact terminals, the socket further comprising:

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, said second pressing member having a second proximal end supported in a moveably rotational manner at another end of said socket body, said second pressing member having a second touch portion coupled to said second proximal end, wherein

the movement of said second proximal end causes said second touch portion to contact said semiconductor device so that said semiconductor device is pressed toward said contact terminals

~~a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion formed at the proximal end while being deviated in one widthwise direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and~~

~~a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.~~

4. (Currently Amended) A socket for a semiconductor device ~~as claimed in claim 1, wherein said socket comprising:~~

a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals, said semiconductor device being one of a plurality of semiconductor devices having contour dimensions different from one another;

a first pressing member having a first touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, said pressing member being driven by a pressing member driving mechanism in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section, for holding said semiconductor device in said semiconductor device placement section;

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, and

wherein, when said pressing member driving mechanism moves said first touch portion of said pressing member to a position in which said first touch portion of said pressing member does not contact said semiconductor device upon the attachment or detachment of said semiconductor device, a portion of said first pressing member is bulged outwardly from an end of said socket body via an opening of said socket body,

~~a first pressing member for holding said semiconductor device in said semiconductor device placement section, having~~ said first pressing member has a first proximal end supported in a moveably rotationally manner at one end of said socket body, ~~and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and~~

~~a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member,~~ having said second pressing member has a second proximal end supported in a moveably rotationally manner at ~~the other~~ another end of said socket body and ~~an a~~ touch portion in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals, and ; wherein

said second pressing member has a recess for allowing a portion of said first pressing member to enter.

5. (Withdrawn) A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a

moveably rotationally manner at one end of said socket body and an touch portion formed at the proximal end while being deviated in one widthwise direction to be in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; and

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of said socket body and an touch portion formed at the proximal end corresponding to said touch portion of said first pressing member while being deviated in said other widthwise direction to be in contact with said semiconductor device so that the semiconductor device is pressed toward said contact terminals.

6. (Withdrawn) A socket for a semiconductor device as claimed in claim 2, wherein said socket comprising:

a first pressing member for holding said semiconductor device in said semiconductor device placement section, having a proximal end supported in a moveably rotationally manner at one end of said socket body and an touch portion in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals; and

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, having a proximal end supported in a moveably rotationally manner at the other end of

said socket body and an touch portion in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals; wherein

said second pressing member has a recess for allowing a portion of said first pressing member to enter.

7. (Withdrawn) A socket for a semiconductor device comprising:

a socket body having a semiconductor device placement section for placing said semiconductor device;

contact terminals, each having a contact portion movable to be close to or away from said semiconductor device placement section, for electrically connecting terminals of said semiconductor device to a signal input/output section via said contact portions; and

a cover member disposed in said socket body in a movable manner for causing the contact portions of said contact terminals to be close to or away from said semiconductor device placement section; wherein

when said cover member moves close to said socket body, the contact portions of said contact terminals are away from said semiconductor device placement section and tip ends of engagement end sections of said contact terminals engaged with said cover member are projected outwardly through an opening of said cover member.

8. (Withdrawn) A socket for a semiconductor device as claimed in claim 7, wherein said cover member is made to move close to said socket body, the tip end of the engagement end section of said contact terminal is made to move rotationally about a predetermined rotary center positioned inside said socket body.

9. (Withdrawn) A socket for a semiconductor device as claimed in claim 7, wherein position of the tip ends of the engagement end sections of said contact terminals disposed on opposite sides of said semiconductor device placement section between the both are different in height each other.

10. (Withdrawn) A socket for a semiconductor device comprising:
a socket body having a semiconductor device placement section for placing said semiconductor device,

contact terminals, each having a contact portion movable to be close to or away from said semiconductor device placement section, for electrically connecting terminals of said semiconductor device to a signal input/output section via said contact portions, and

a lever member disposed in said socket body in a moveably rotational manner for causing the contact portions of said contact terminals to be close to or away from said semiconductor device placement section, and

a cover member disposed in said socket body in a movable manner for moving rotationally said lever member, wherein

when said cover member is made to move close to said socket body, the contact portion of said contact terminal is away from said semiconductor device placement section and one end of said lever member engaged with said cover member is projected outwardly through an opening of said cover member.

11. (Withdrawn) A socket for a semiconductor device as claimed in claim 10, wherein the inner peripheral surfaces of said cover members for guiding one ends of

said lever members disposed on opposite sides of said semiconductor device placement section have inclinations different from each other, respectively, and at positions at which an end of the inner peripheral surface of said cover member intersects the outer peripheral surface of said cover member is different in height in correspondence to the opposite lever members each other.